

Silicone Foam



Features:

1. Excellent wet-out properties and low flowability, effectively filling uneven gaps.
2. Minimal interfacial thickness and low thermal impedance.
3. No preheating required, suitable for manual coating or screen printing.

Applications:

Filling gaps between CPUs, GPUs, and heatsinks.

Model	Density, kg/m ³	Thickness, mm	Compression Set, at 50%, 100°C	Elongation	Flame Rating, UL 94	Operating Temp., °C
JSSA-700-200	200	1.6~20.0	< 5%	60%	V-0, HF-1	-55~220
JSSA-700-260	260	1.2~20.0	< 5%	70%	V-0, HF-1	-55~220
JSSA-700-300	300	1.2~20.0	< 5%	60%	V-0, HF-1	-55~220
JSSA-700-350	350	0.6~20.0	< 5%	90%	V-0, HF-1	-55~220
JSSA-700-400	400	1.0~12.0	< 5%	80%	V-0, HF-1	-55~220